



100% Material Declaration Data Sheet for 7 Series FTG256 Package

PK626 (v1.0) April 12, 2014

Average Weight: 0.7590 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.028393	3.741%
	Silicon	7440-21-3	100.00		0.028393	
Die Attach Epoxy					0.008859	1.167%
	Silver	7440-22-4	77.50		0.006866	
	Bismaleimide monomer	Trade Secret	15.00		0.001329	
	Acrylate monomer	Trade Secret	7.50		0.000664	
Mold Compound					0.373823	49.252%
	Epoxy Resin	Trade Secret	5.00		0.018691	
	Phenol Resin	Trade Secret	3.00		0.011215	
	Phenol Novalac	9003-35-4	3.00		0.011215	
	Metal Hydroxide	Trade Secret	3.00		0.011215	
	Carbon black	1333-86-4	0.30		0.001121	
	Silica fused	60676-86-0	70.40		0.263171	
	Silica fused	7631-86-9	15.00		0.056073	
Silica, crystalline	14808-60-7	0.30		0.001121		
Copper Wire					0.004907	0.647%
	Copper	7440-50-8	98.25		0.004821	
	Palladium	7440-05-3	1.75		0.000086	
Solder Ball					0.123758	16.305%
	Tin	7440-31-5	96.50		0.119426	
	Silver	7440-22-4	3.00		0.003713	
	Copper	7440-50-8	0.50		0.000619	
Substrate					0.219258	28.888%
	Gold	7440-57-5	0.24		0.000537	
	Nickel	7440-02-0	1.44		0.003149	
	Copper Foil	7440-50-8	40.42		0.088630	
	Copper Plating	7440-50-8	13.75		0.030139	
	Continuous Filament Fiber Glass	65997-17-3	16.82		0.036888	
	Non Halogen fire retardant	Trade Secret	0.01		0.000022	
	BT Core	Trade Secret	20.56		0.045085	
Solder Mask	Trade Secret	6.75		0.014808		

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
04/12/2014	1.0	Initial Xilinx release.

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